



2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Kuo-Yu Chou
SERIAL NO.: 10/043,709
FILED: 01/09/2002
TITLED: A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM AL FILM THICKNESS
IN CU/FSG PROCESS FOR DEVICES UNDER PADS

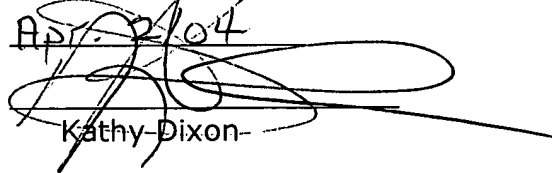
EXAMINER: Le, Thao X.
ART UNIT: 2814
ATTY DKT NO.: 67,200-603

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CERTIFICATE OF MAILING

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Kathy Dixon

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Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
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RESPONSE UNDER 37 C.F.R. §1.111

Dear Sir:

In response to the Office Action dated January 5, 2004 (Paper No. 1203) in
the above captioned matter, please enter the following remarks: